High-Performance Mixed-Signal Controllers for On-Chip Integrated SMPS

Aleksandar Prodic

E-mail: prodic@ele.utoronto.ca



Introduction

- Volume occupied by low-power SMPS in today's applications
- On-chip implementation challenges
- Mixed-signal control method for system (overall application) minimization
 - Ultra high frequency digital control
 - Minimum deviation control
 - Load interactive SMPS



Low-Power Switch Mode Power Supplies (SMPS)





- Power from a fraction of a watt to hundreds of watts
- Usually parts of a multi-supply power management systems
- Partially integrated and often take up to 30% of the total device volume/area

Volume/area Taken by the Reactive Components





More than a 25% of the motherboard (or other device) can be taken by the LC components of the SMPS

Reliability and Size Issues: Existing 3-Chip Solutions



• Three chip solutions implemented in different technologies usually used (low flexibility, significant size, reliability, pin count...)



• Difficulties in implementing power management techniques such as dynamic and adaptive voltage scaling (AVS/DVS)

System Level Architecture



• Two or a single chip solution for system integration



• Mixed-signal controller enables system minimization

Mixed-Signal Controller



Mixed-signal controller enables system integration through:

- Operation at ultra high switching frequencies
- Minimum deviation response to load transients (Cap sized based on transients)
- Interaction with the load, ideally, allowing C to be sized based on ripple only

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Ultra-High Frequency Digital Controller



ADC



Digital controller supporting operation at switching frequencies of several hundreds of MHz is available ^[1]

[1] Z. Lukić, N. Rahman, and A. Prodić, "Multi-Bit Sigma-Delta PWM Digital Controller IC for DC-DC Converters Operating at Switching Frequencies Beyond 10 MHz," IEEE Transactions on Power Electronics, September 2007, Vol.22, Issue 5, pp. 1693-1707 University of Toronto, ECE Department

Minimum (Optimum) Deviation Controller



• Operates on principle that is not directly BW related



• *Requires no knowledge of power stage parameters*

• Minimizes current stress

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Practical Implementation Challenges



- Accurate and fast detection of transient and valley points is required
- Mode transition stability problems due to mismatch in pre and post transient steady state duty ratio values





- *Two comparators form a no-loaded capacitor window around steady state value*
- Dual-valley point detection performed to minimize error



Duty Ratio Value Correction



• Due to D mismatch even for a highly efficient converter a deviation larger than that due to the transient can occur

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Controller Response & On-Chip Implementation



- *Physical limit of a given power stage, about 4 x smaller cap compared to* 1/10 PID
- Simpler implementation than time-optimal + no knowledge of parameters needed University of Toronto, ECE Department

Load Interactive Digitally Controlled SMPS



• Non-inverting buck-boost power stage modified with an addition of extra switch (recycling switch)



• Communication with the load giving a pre-load command established to pre-charge inductor to a value closer to the new load current prior the transient University of Toronto, ECE Department 14

Pre-Load/ Post-Load Conditions



• Light-to-heavy pre-load

• Heavy-to-light post-load



Control Algorithm





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Transient Performance



• Top: time-optimal

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Bottom: load-interactive (theoretically allowing reduction limited by ripple only) only
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Conclusion

• Mixed signal control methods can bring us few steps closer to a full on-chip implementation of SMPS, potentially allowing output capacitor and inductor to be sized based on physical limitation of the converter or even on the ripple requirements only

• Better interconnection with loads can potentially result in about 25% reduction of the overall system size including both power supplies and the supplied devices

